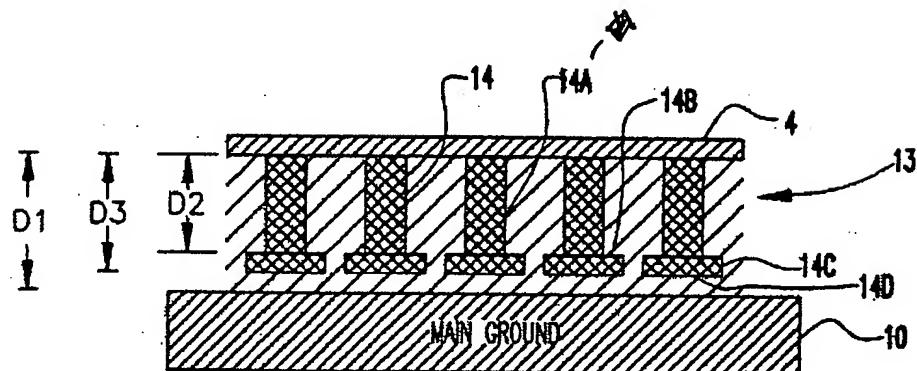


Waffle-Iron Waveguide Filter: (a) view looking into port 2, (b) exploded view.

Prior Art

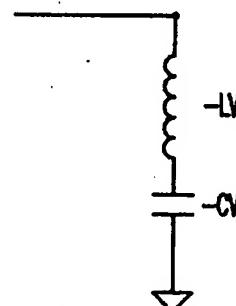
FIG. 1



Examples of resonant vias from Riad's US patent 5,886,597.

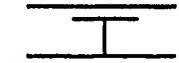
Prior Art

FIG. 2



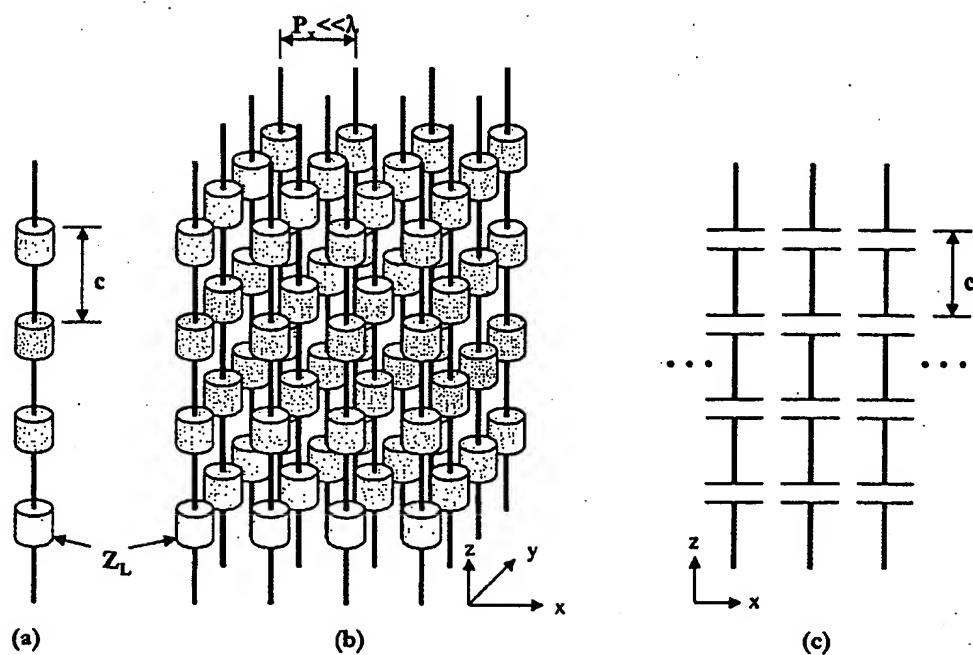
Prior Art

FIG. 3

	Mechanically-Unbalanced	Mechanically-Balanced
Internal	Internal "T"  US Pat. 5,886,597	Internal "double T"  US Pat. 6,542,342 Internal "T" 
External	External "T"  US Pat. 5,886,597	External "T" 
Hybrid		Hybrid "I" 

Examples of resonant vias. Dielectric layers required for support are not shown.

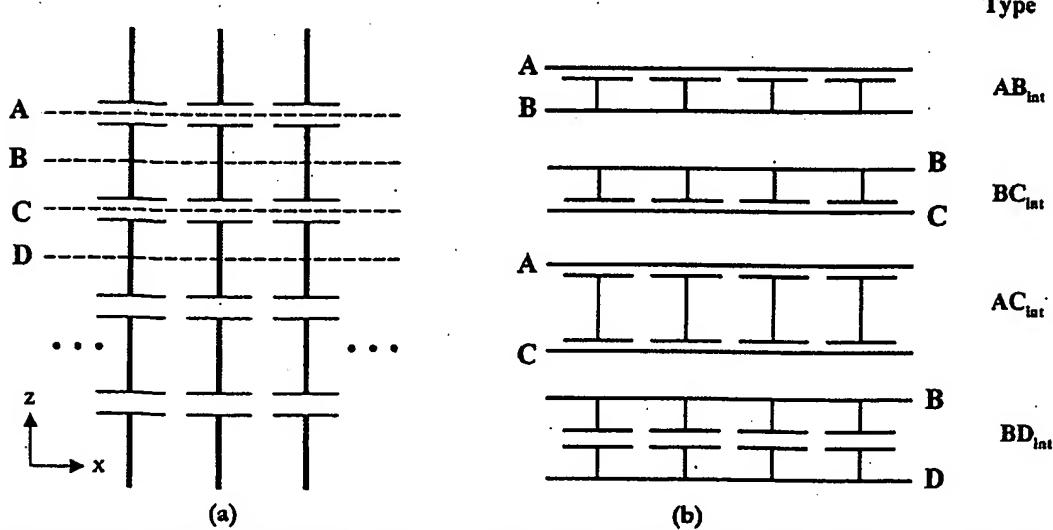
FIG. 4



The starting point for the derivation of new inventions is the loaded wire media: (a) a single wire with uniform periodic series loads, (b) a rectangular array of loaded wires, (c) loads are now defined as parallel-plate capacitors.

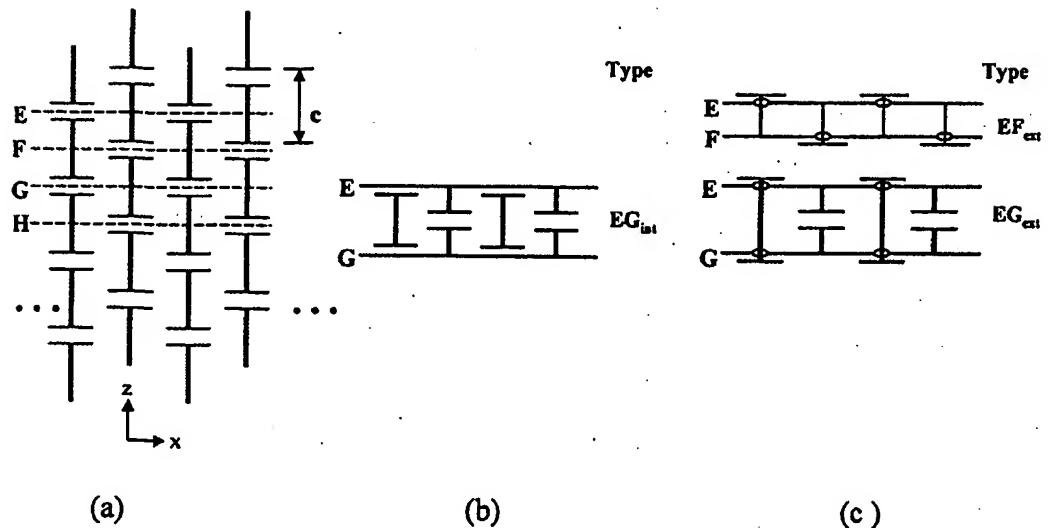
Prior Art

FIG. 5



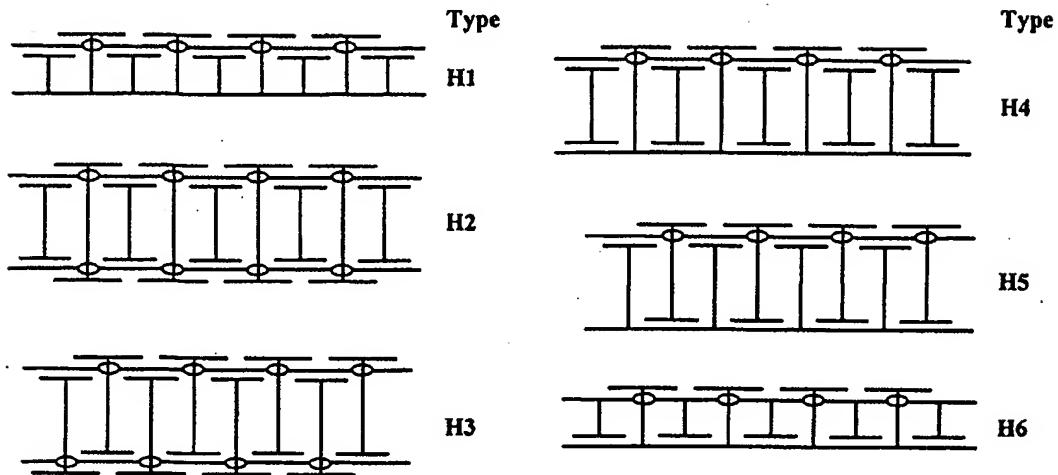
Exploit the planes of physical symmetry to obtain electromagnetically equivalent structures: (a) the infinite wire media, (b) PPW structures of finite height. The supporting dielectric structure is not shown.

FIG. 6



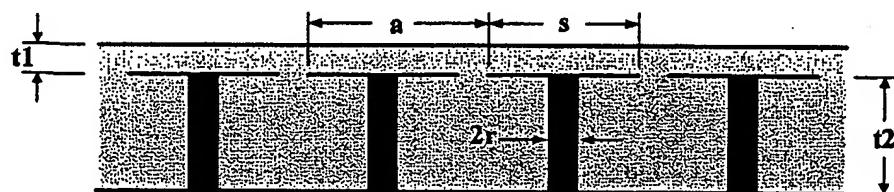
Alternative embodiments of PPW stop band filters: (a) Capacitive-loaded infinite wire media, (b) a PPW filter of finite height using internal capacitors, (c) PPW filters of finite height using external capacitors. The supporting dielectric structure is not shown.

FIG. 7



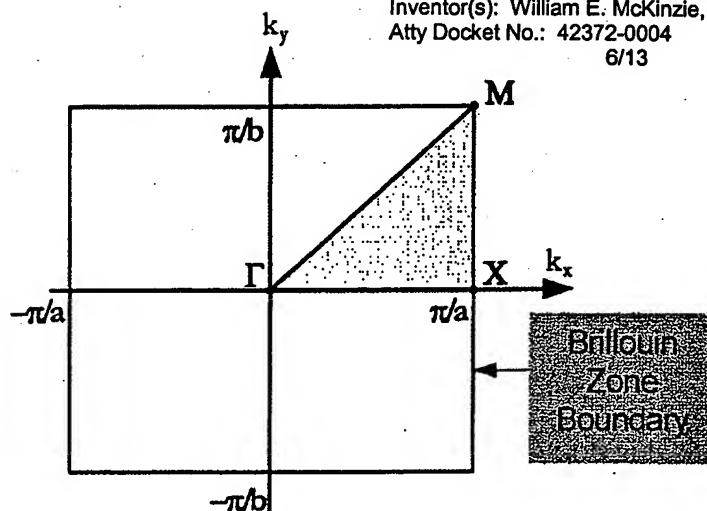
Hybrid embodiments include combined internal and external capacitive loads. Dielectric cores are omitted for clarity.

FIG. 8



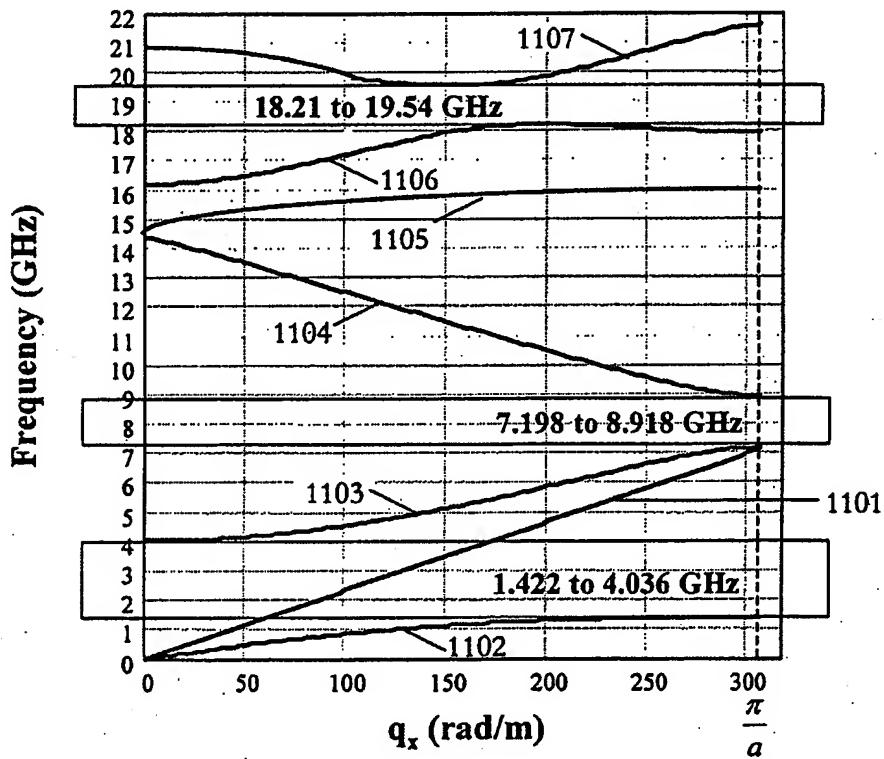
Elevation view of a square lattice of internal T resonant vias.

FIG. 9



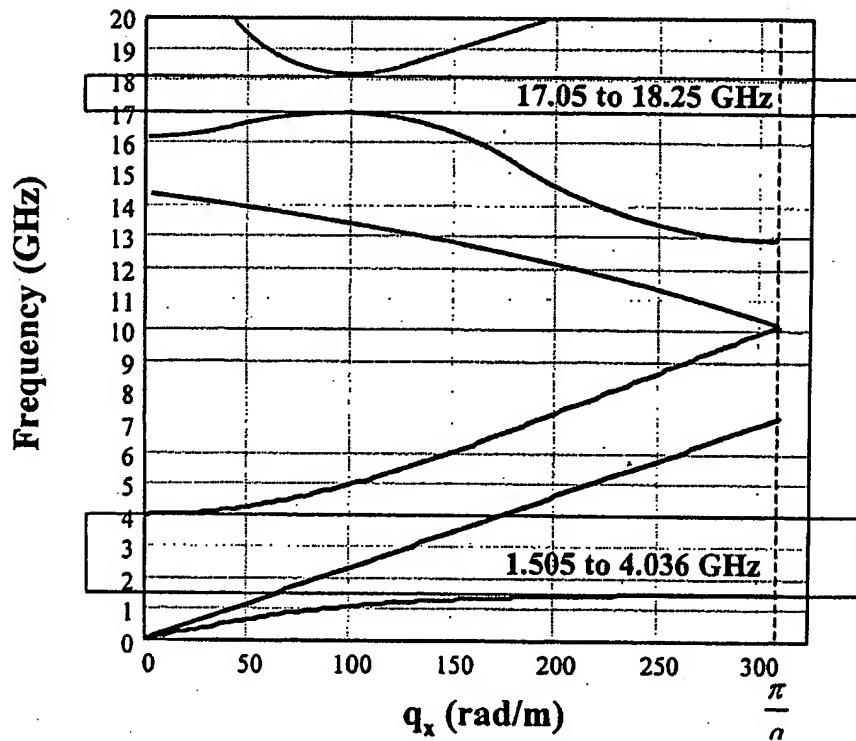
Brillouin zone for a 2D periodic structure with a rectangular lattice of unit cell dimensions  $a \times b$  in Cartesian coordinates.

FIG. 10



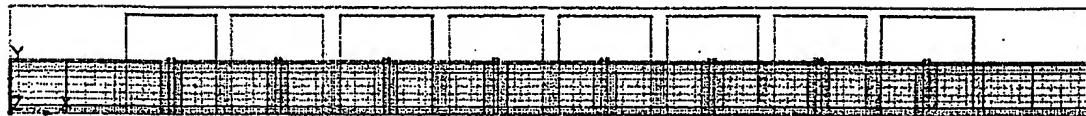
Dispersion diagram along the  $\Gamma X$  line for the capacitive-loaded wire media corresponding to the array of resonant vias shown in Figure 9. The stop bands are bracketed.

FIG. 11

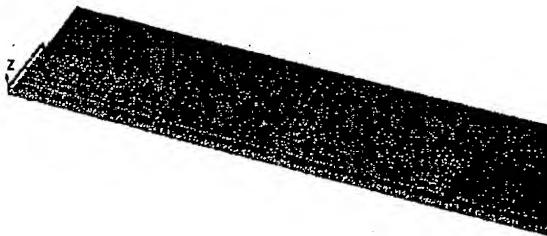


Dispersion diagram along the  $\Gamma M$  line for the capacitive-loaded wire media corresponding to the array of resonant vias shown in Figure 9. The stop bands are bracketed.

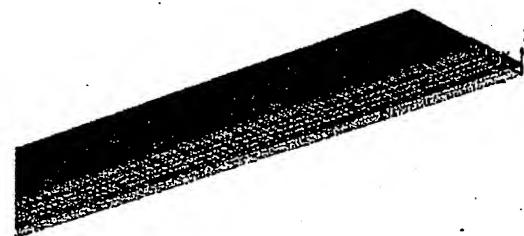
FIG. 12



(a)



(b)

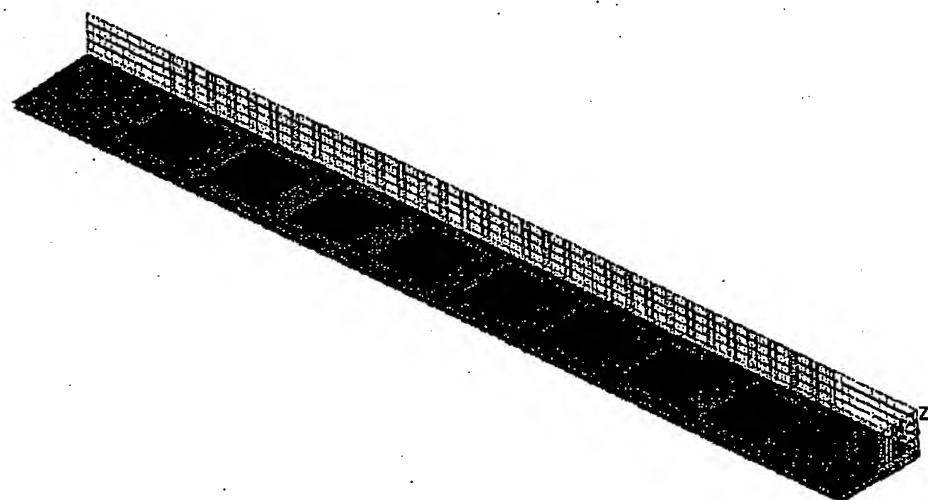


(c)

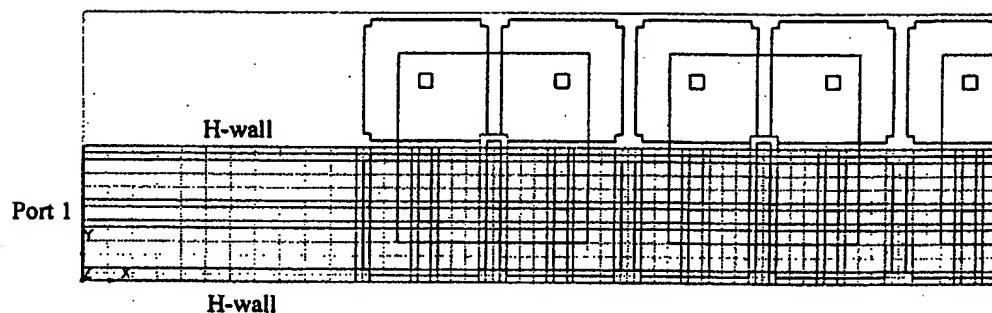
Geometry for the simulation of the resonant via array shown in Figure 9: (a) plan view showing all 8 cascaded unit cells, (b) top view with upper plate hidden, (c) bottom view with the lower plate hidden.

**FIG. 13**

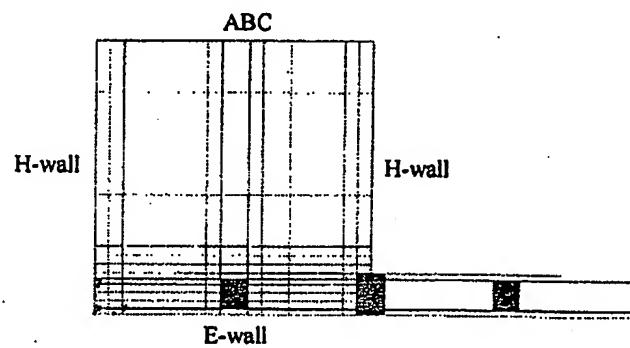
Heller Ehrman LLP  
Title: "SYSTEMS AND METHODS FOR BLOCKING  
MICROWAVE PROPAGATION IN PARALLEL PLATE  
STRUCTURES"  
Application No.: 10/796,398 – Filed: 03/08/2004  
Inventor(s): William E. McKinzie, III  
Atty Docket No.: 42372-0004  
9/13



(a)



(b)

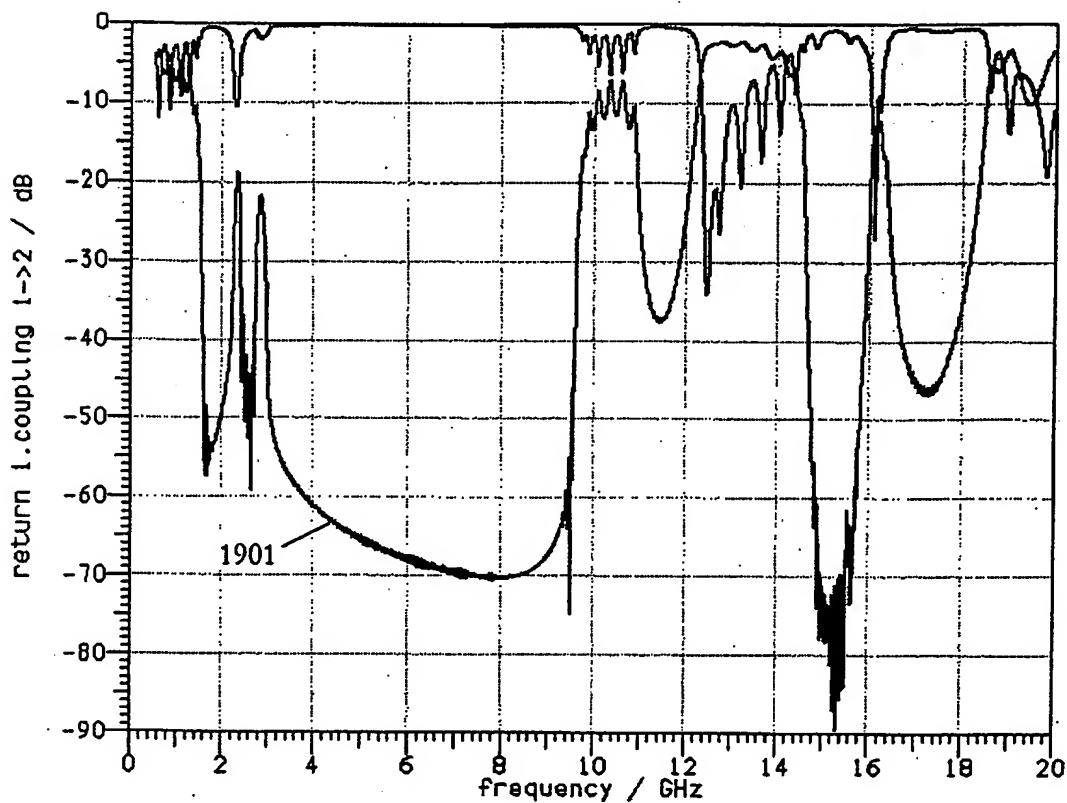


(c)

Geometry for the simulation of a commensurate period resonant via array of type H12: (a) perspective view showing all 8-cascaded unit cells, (b) plan view, (c) elevation view. Hidden are the dielectric cores in (a), (b) and (c).

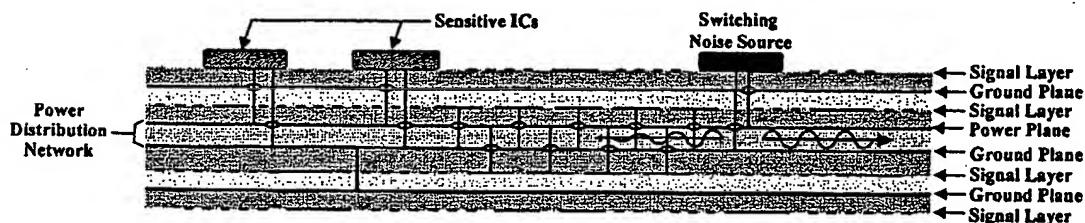
FIG. 18

Lossy T20



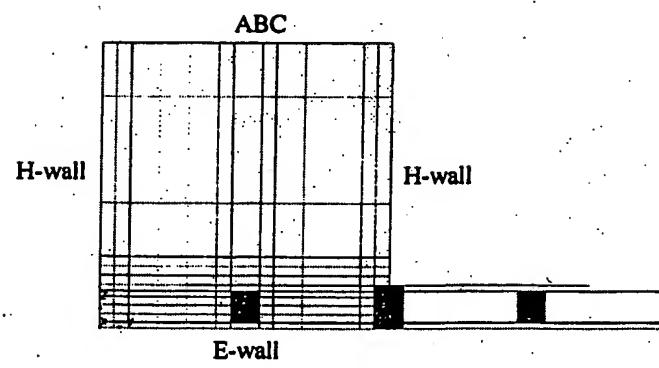
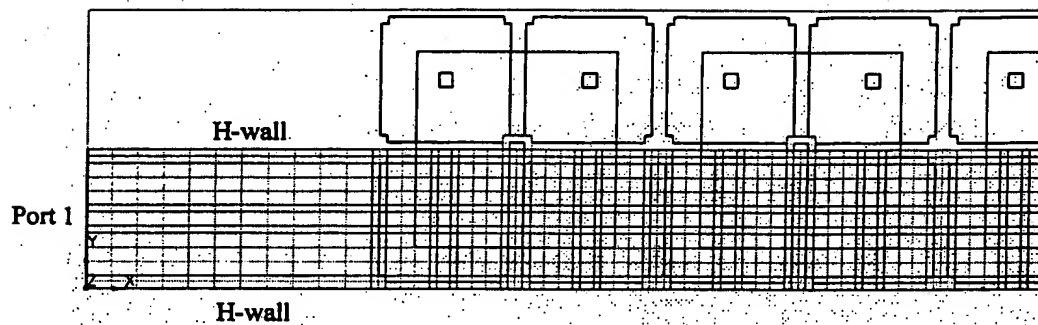
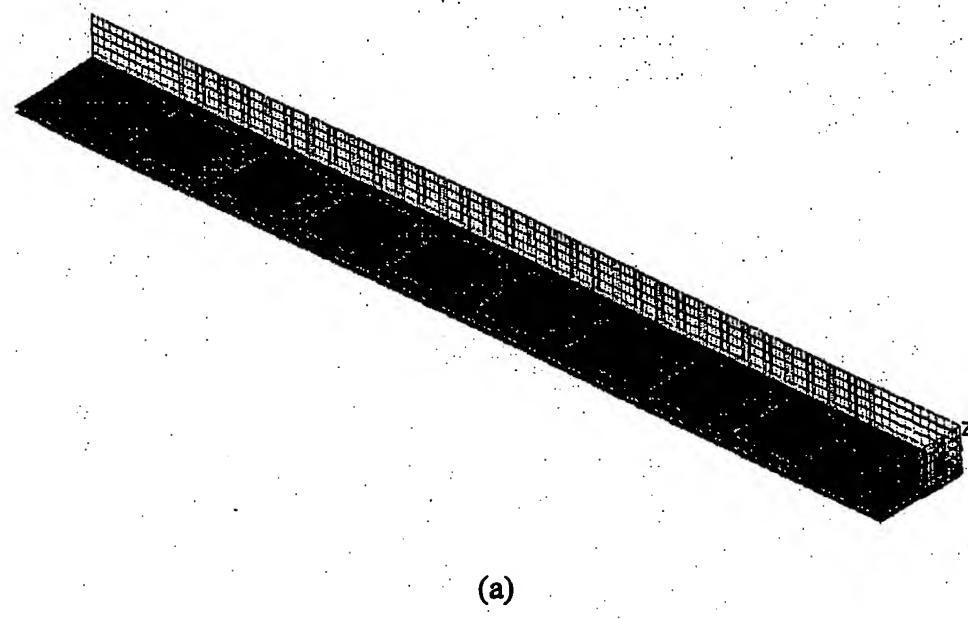
Transmission response (1901) for a TEM mode propagating in the x direction through the stop band filter shown in Figure 18. A -10 dB stop band is shown from 1.33 GHz to 10.0 GHz, a 7.5:1 ratio.

FIG. 19



Stop band filter embodiment  $EF_{ext}$  is well suited for integration into existing PWB designs since it requires neither additional metal layers nor any additional thickness.

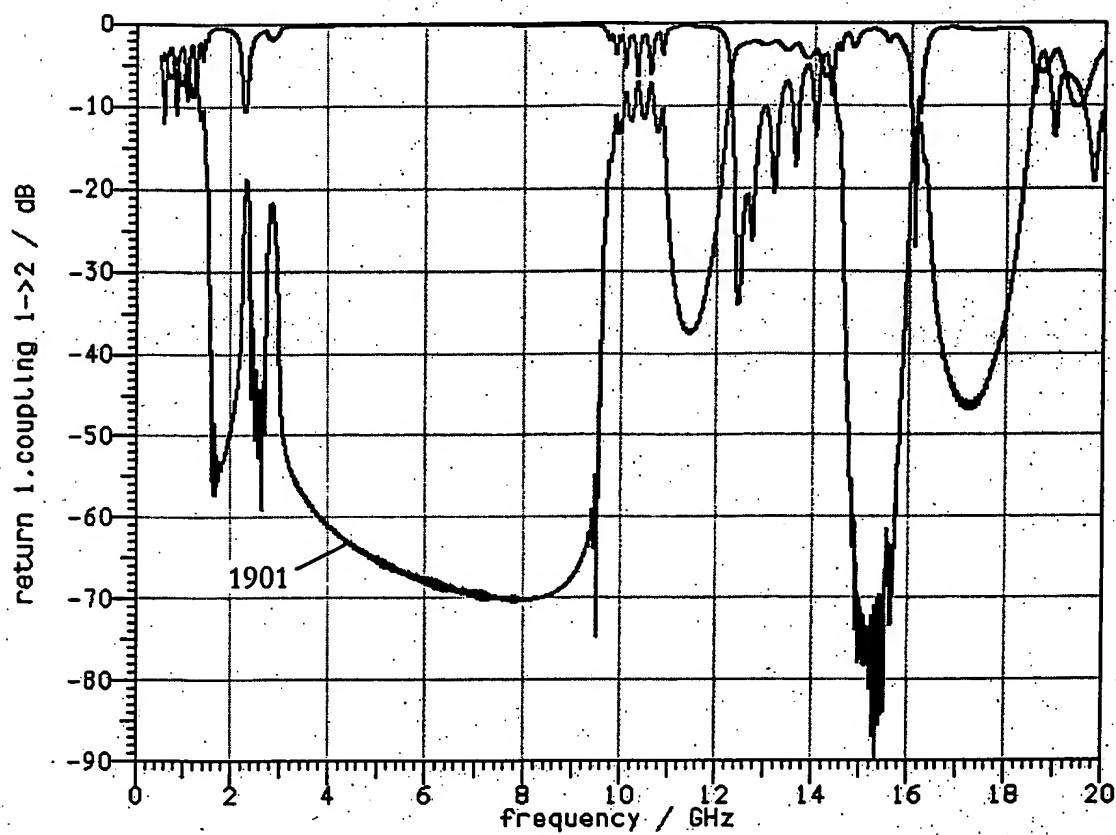
FIG. 20



Geometry for the simulation of a commensurate period resonant via array of type H12: (a) perspective view showing all 8-cascaded unit cells, (b) plan view, (c) elevation view. Hidden are the dielectric cores in (a), (b) and (c).

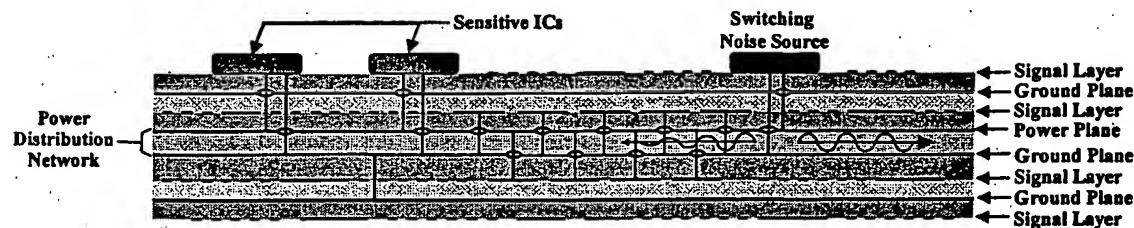
FIG. 18

Lossy T20



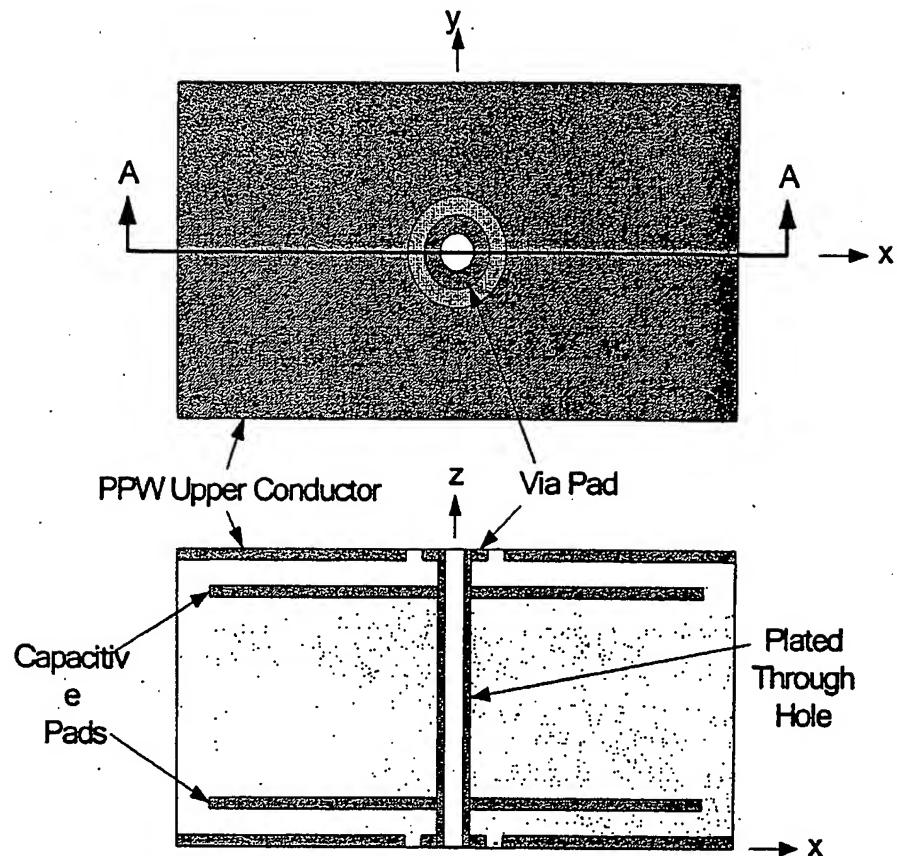
Transmission response (1901) for a TEM mode propagating in the x direction through the stop band filter shown in Figure 18. A -10 dB stop band is shown from 1.33 GHz to 10.0 GHz, a 7.5:1 ratio.

FIG. 19



Stop band filter embodiment  $EF_{ext}$  is well suited for integration into existing PWB designs since it requires neither additional metal layers nor any additional thickness.

FIG. 20



Plated through holes may be used in the fabrication of resonant vias as illustrated here for an internal I resonant via.

FIG. 21

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